

# RRW22111-153+IW610-08+RRW30110-190 FOR 65W PD3.2 ZSP DESIGN EBC10296

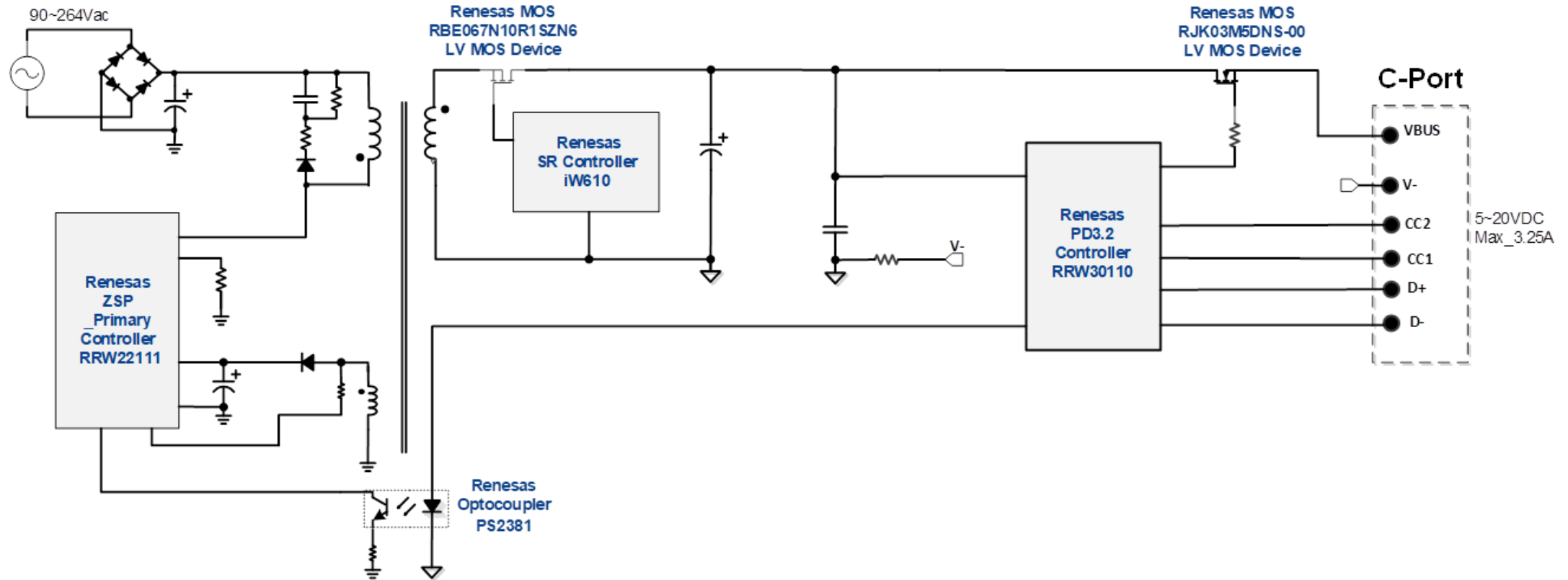
## GENERAL DESIGN SPECIFICATION:

1. AC INPUT RANGE: 90-264V<sub>AC</sub>
2. DC OUTPUT: 5-20V/3.25A WITH E-MARK CABLE
3. MEET BOTH “COC\_V5\_TIER2” AND “DOE VII” EFFICIENCY REQUIREMENT
4. STANDBY POWER <5mW
5. SUPPORT PD3.2
6. INTEGRATED GaNFET APPLICATION

NOTE: This reference design document is intended as a design idea to show potential capability of this integrated circuit device. Evaluation boards may not be available.

August 2025; Rev. 1.1

# BLOCK DIAGRAM OF EBC10296



# WARNING

## DISCLAIMER FOR HIGH VOLTAGE (MAINS POWERED) EVALUATION BOARDS

### Warning

This evaluation board is powered by AC mains voltage. When powered, this evaluation board generates non-insulated high voltages which may produce electrical shock, burn, and/or fire hazards, resulting in risk of property damage, personal injury, and/or death.

**When the evaluation board is powered, never touch the board or its electrical circuits since they may be operating at high voltages that can cause an electrical shock hazard.**



### TO BE USED FOR EVALUATION PURPOSES ONLY

This board is intended for evaluation purposes only and not intended for commercial use in an end product. Any other use is strictly prohibited by Renesas Electronics Corporation and its Subsidiaries (“Renesas”).

### WORK AREA AND PERSONAL SAFETY

This board should be used in a test area/laboratory specifically designed and designated for working with, and evaluating high-voltage electrical devices. Only trained and qualified professional personnel with experience, knowledge and training in the use of high-voltage electrical circuits should use this evaluation board. Trained personnel must use required personal protective equipment and required laboratory equipment when working with the evaluation board.

The professional personnel operating this evaluation board and the test area/laboratory in which it is operated must be qualified according to the local regulations, guidelines and labor laws applicable to working with non-isolated mains voltages and high voltage circuits.

An isolated housing is highly recommended when using this evaluation board.

Use this evaluation board at your own risk.

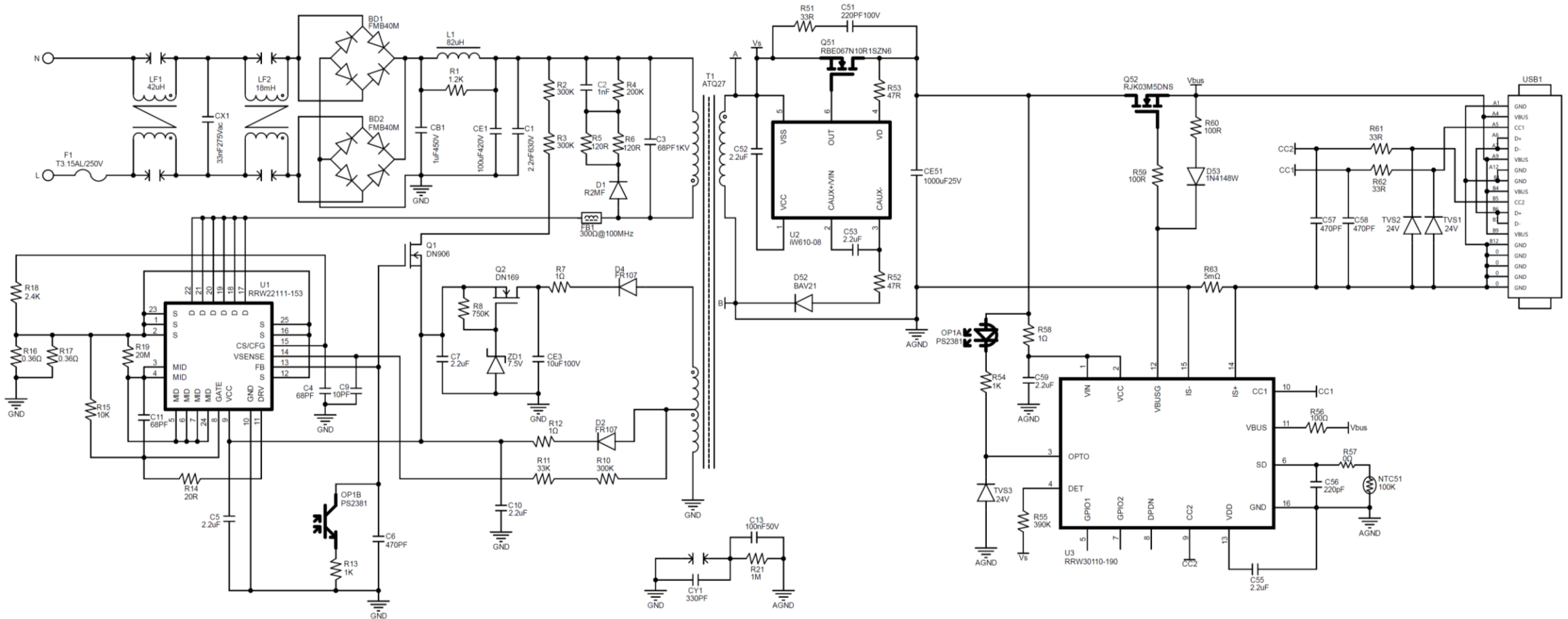
### NOT AGENCY APPROVED

This evaluation board has not been agency tested or approved for safety, technical performance, and/or regulatory requirements, such as electromagnetic interference or other technical regulatory or safety requirements.

# 1. GENERAL SPECIFICATION

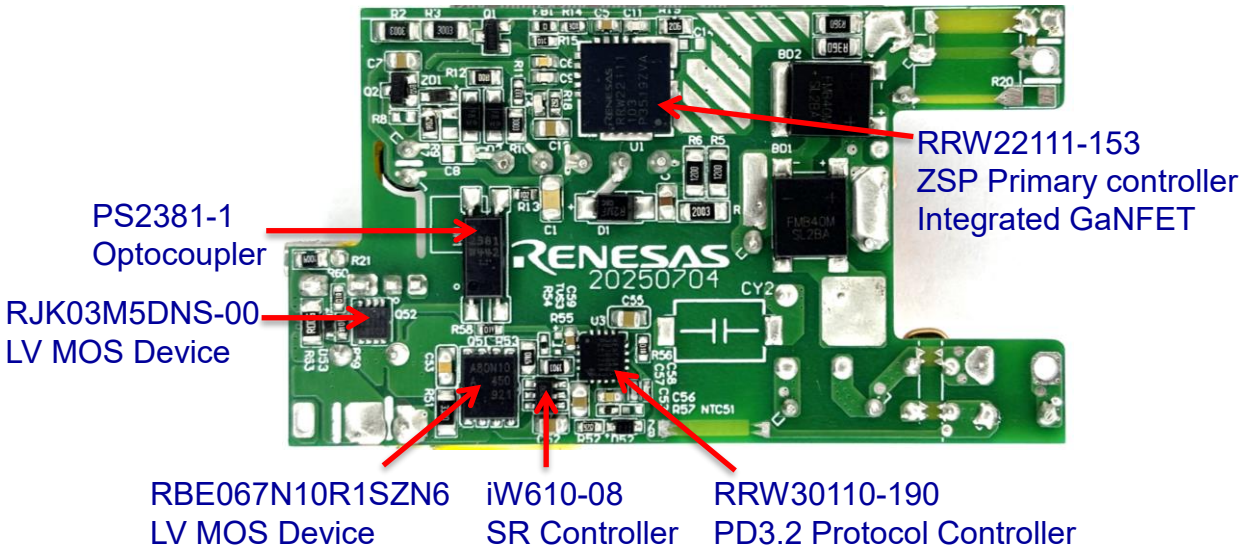
Description	Symbol	Min	Typ	Max	Units	Comment
Input Voltage	$V_{IN}$	90		264	V <sub>AC</sub>	2 Wire
Frequency	$f_{LINE}$	47	50/60	63	Hz	
No-load Input Power (230V <sub>AC</sub> )				5	mW	
Output Voltage	$V_{OUT\_CV}$	5		20	V	Measured at PCB-end
Output Current	$I_{OUT}$	0		3.25	A	Power limit (65W_Max)
Protocol		Meets PD3.2				
Ripple & Noise	$V_{RIPPLE}$			200	mV <sub>P_P</sub>	Add 0.1uF Ceramic capacitor and 10uF E-cap at the end of cable and set oscilloscope at 20MHz bandwidth.
Over Current Protection	$I_{OCP}$			3.9	A	
Conducted EMI		Meets FCC Part 15B / EN55032B				Output is Connected to Ground
Safety		Designed to meet IEC60950, UL1950 Class II				
Ambient Temperature	$T_{AMB}$	0		25	° C	Free convection, sea level

# 2. SCHEMATIC

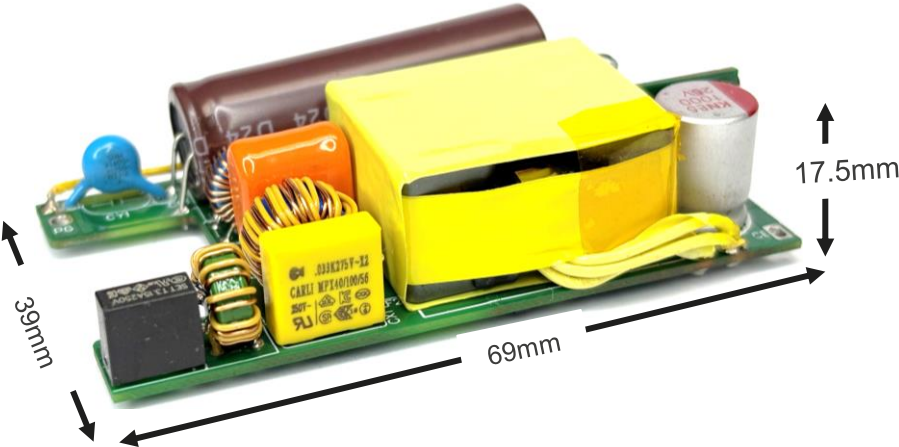


# 3. CIRCUIT BOARD PHOTOGRAPH

Bottom View

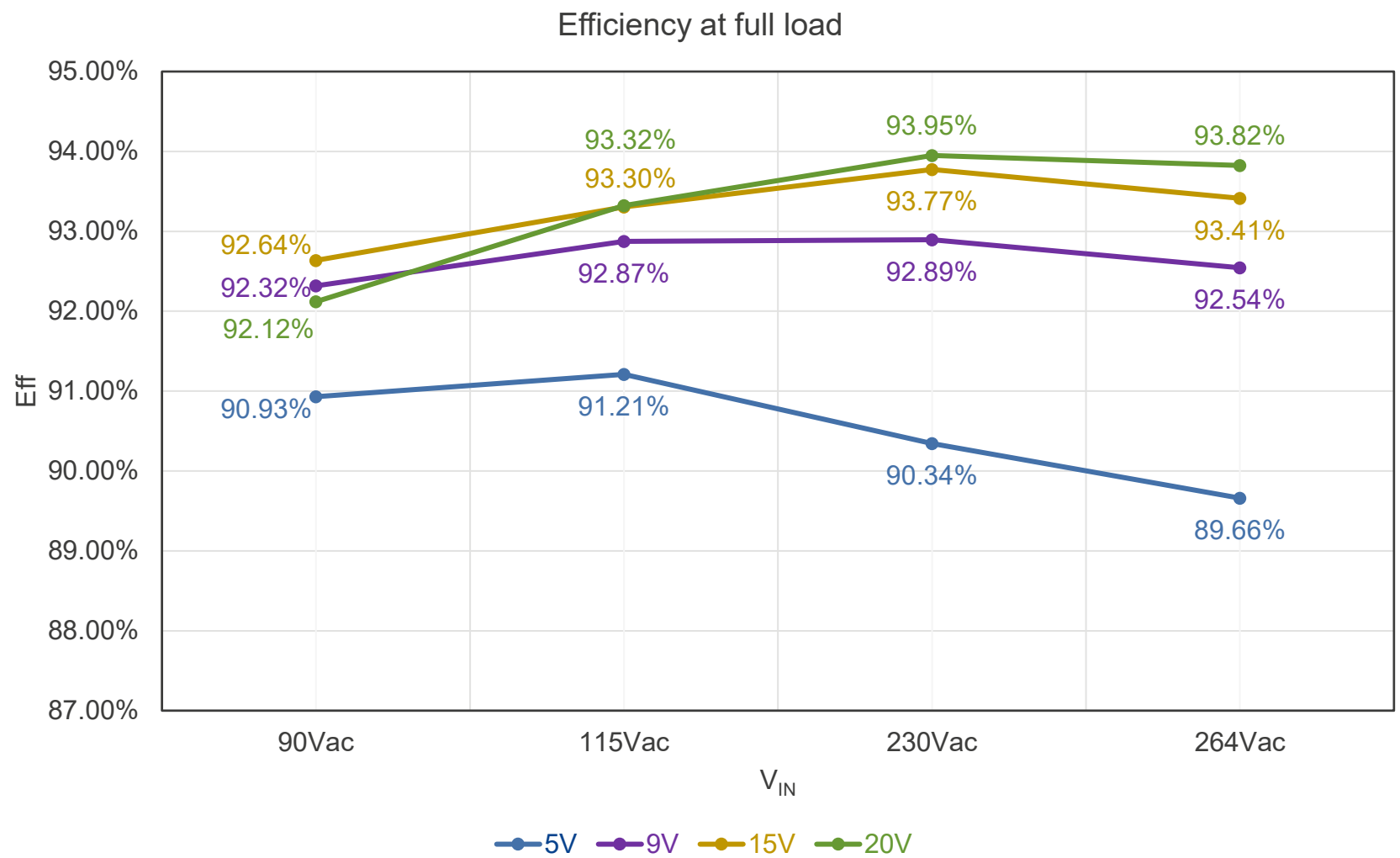


Top View



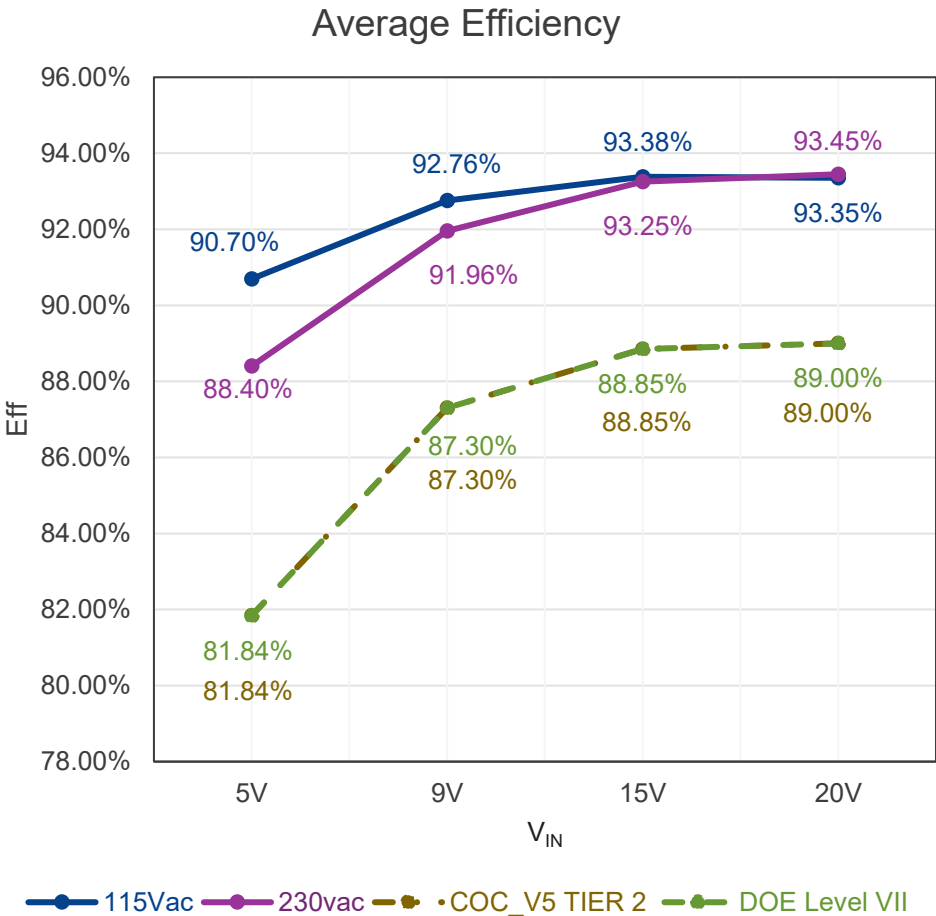
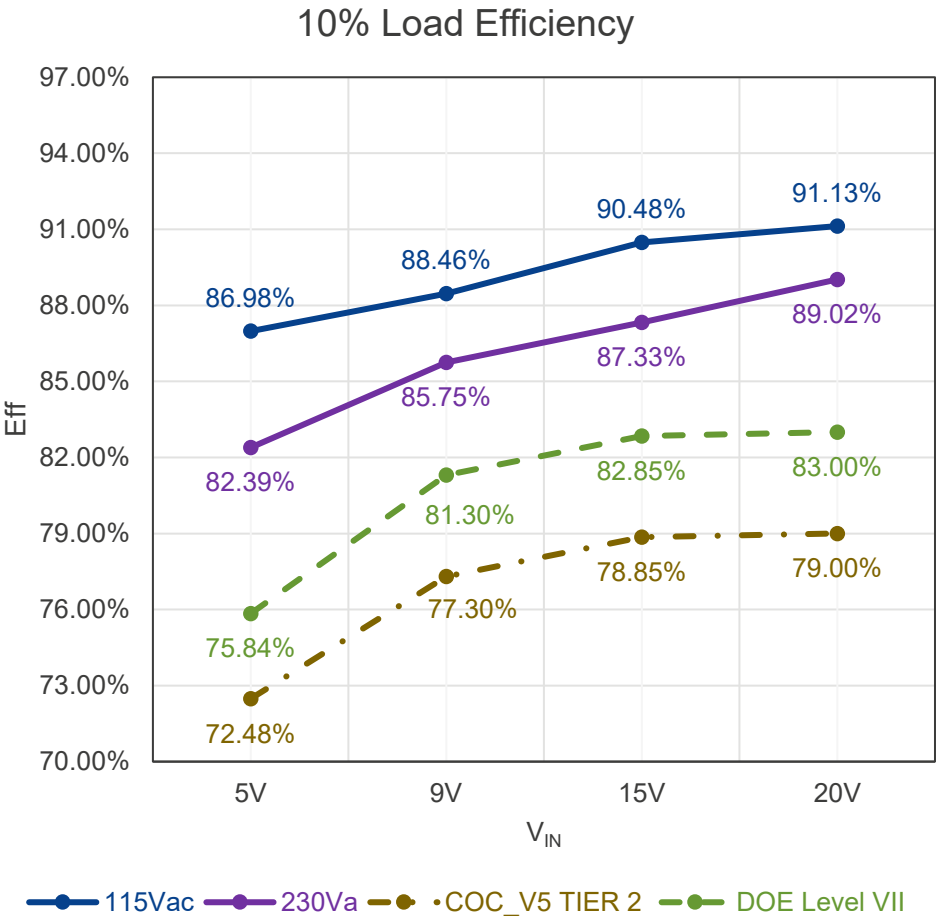
Ultra-Thin Design, Power Density: 1.38w/cm<sup>3</sup>

# 4. EFFICIENCY AT FULL LOAD



\*Note: The output voltage is measured at PCB-end.

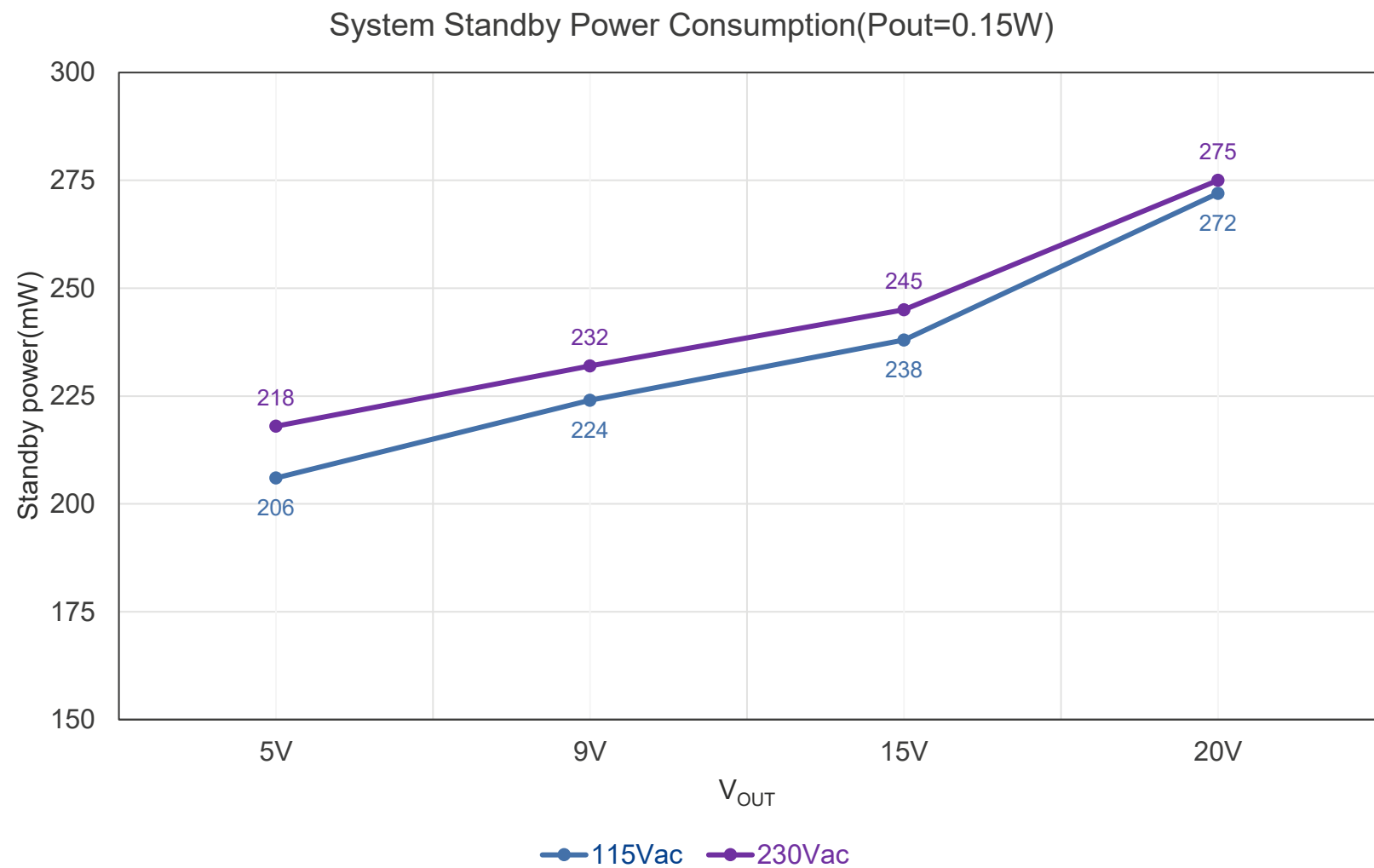
# 5. ACTIVE MODE EFFICIENCY



\*Note: The output voltage is measured at PCB-end.

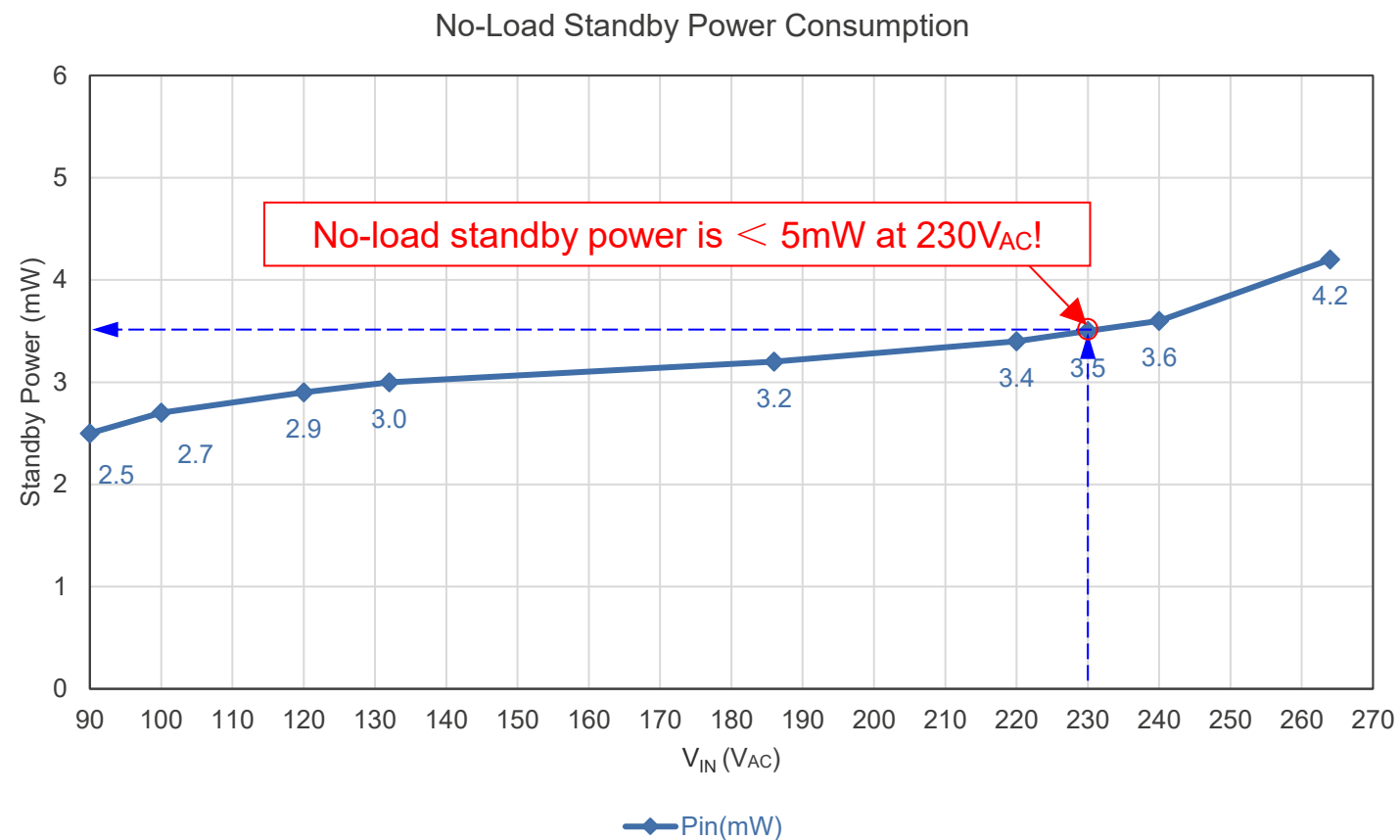


# 6. SYSTEM STANDBY POWER CONSUMPTION



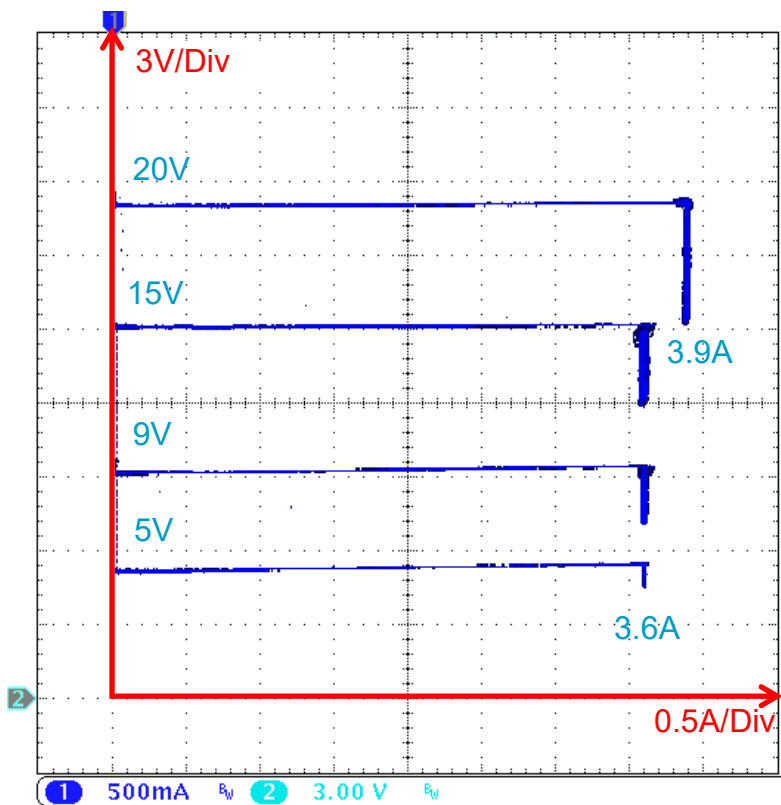
\*Note: The output voltage is measured at Cable-end.

# 7. NO-LOAD STANDBY POWER

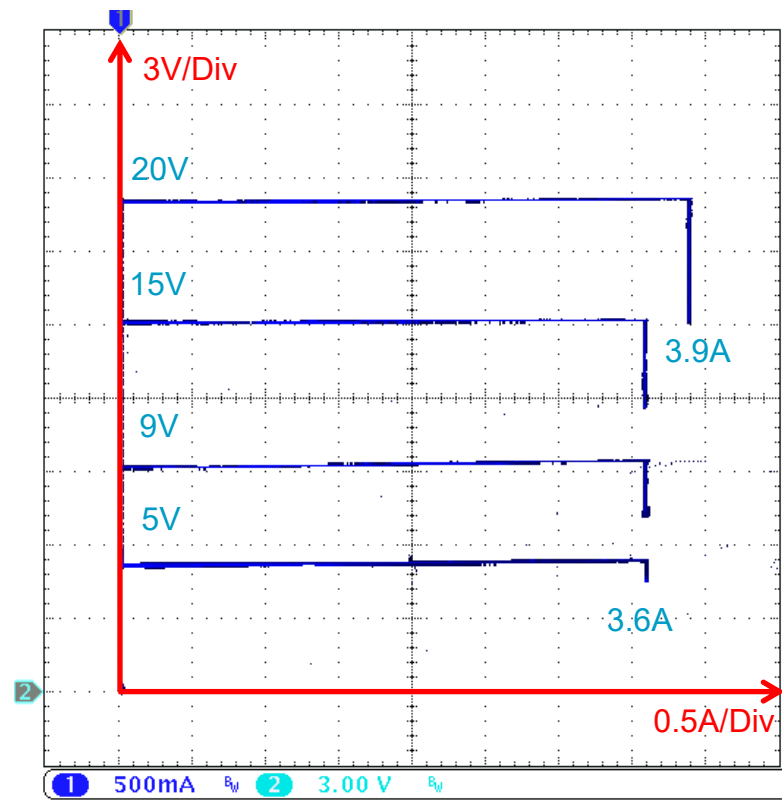


# 8. OUTPUT VI CHARACTERISTICS

$V_{IN}=90V_{AC}/60Hz$



$V_{IN}=264V_{AC}/50Hz$



\*Note: The output voltage is monitored at PCB-end.

# 9. OUTPUT VOLTAGE RIPPLE

$V_{IN}$	$I_{OUT}$ $V_{OUT}$	0A	0.3A	0.75A	1.5A	2.25A	3A	3.25A
115V <sub>AC</sub>	5V	84mV	104mV	70mV	110mV	124mV	118mV	N/A
	9V	94mV	102mV	76mV	96mV	100mV	110mV	N/A
	15V	90mV	64mV	82mV	90mV	104mV	122mV	N/A
	20V	80mV	72mV	78mV	88mV	114mV	132mV	152mV
230V <sub>AC</sub>	5V	94mV	114mV	94mV	104mV	128mV	124mV	N/A
	9V	92mV	126mV	72mV	110mV	100mV	114mV	N/A
	15V	96mV	58mV	84mV	88mV	96mV	120mV	N/A
	20V	82mV	70mV	86mV	90mV	112mV	114mV	124mV

\*Note:

1. Add 0.1uF Ceramic capacitor and 10uF E-cap at the end of cable(150mohm).
2. Set oscilloscope to 20MHz bandwidth.

# 10. DYNAMIC LOAD RESPONSE

Dynamic Load Condition			5V/9V/15V 0A-2.7A-0A and 20V 0A-2.93A-0A, Slew:2.5A/us				
			1Hz	10Hz	100Hz	1kHz	5kHz
5V (4.5V<Vo<5.5V)	90V <sub>AC</sub> / 60Hz	V <sub>O_MIN</sub> (V)	4.60	4.60	4.60	4.80	4.64
		V <sub>O_MAX</sub> (V)	5.38	5.38	5.36	5.40	5.28
	264V <sub>AC</sub> / 50Hz	V <sub>O_MIN</sub> (V)	4.62	4.60	4.62	4.68	4.64
		V <sub>O_MAX</sub> (V)	5.38	5.40	5.34	5.38	5.28
9V (8.1V<Vo<9.9V)	90V <sub>AC</sub> / 60Hz	V <sub>O_MIN</sub> (V)	8.56	8.52	8.54	8.62	8.64
		V <sub>O_MAX</sub> (V)	9.40	9.40	9.38	9.36	9.32
	264V <sub>AC</sub> / 50Hz	V <sub>O_MIN</sub> (V)	8.54	8.54	8.56	8.70	8.64
		V <sub>O_MAX</sub> (V)	9.38	9.42	9.36	9.34	9.32
15V (13.5V<Vo<16.5V)	90V <sub>AC</sub> / 60Hz	V <sub>O_MIN</sub> (V)	14.6	14.6	14.5	14.5	14.6
		V <sub>O_MAX</sub> (V)	15.4	15.4	15.4	15.4	15.4
	264V <sub>AC</sub> / 50Hz	V <sub>O_MIN</sub> (V)	14.6	14.5	14.5	14.6	14.6
		V <sub>O_MAX</sub> (V)	15.4	15.4	15.4	15.5	15.4
20V (18V<Vo<22V)	90V <sub>AC</sub> / 60Hz	V <sub>O_MIN</sub> (V)	19.5	19.5	19.4	19.5	19.6
		V <sub>O_MAX</sub> (V)	20.5	20.5	20.5	20.5	20.4
	264V <sub>AC</sub> / 50Hz	V <sub>O_MIN</sub> (V)	19.5	19.5	19.4	19.5	19.6
		V <sub>O_MAX</sub> (V)	20.4	20.5	20.5	20.5	20.4



Dynamic Load  
esponse Waveforr

\*Note

1. The output voltage is measured at Cable-end.
2. The cable impedance is 150mohm.
3. Refers to detail waveform as enclosed file.

# 11. PEAK LOAD RESPONSE

Output	Peak Power Condition: Frequency: 1Hz Slew-Rate: 2.5A/us	V <sub>OUT</sub> Limits		90V <sub>AC</sub> / 60Hz		264V <sub>AC</sub> / 50Hz	
		V <sub>O_MIN</sub> (V)	V <sub>O_MAX</sub> (V)	V <sub>O_MIN</sub> (V)	V <sub>O_MAX</sub> (V)	V <sub>O_MIN</sub> (V)	V <sub>O_MAX</sub> (V)
5V	Load: 15W(999ms) – 22.5W(1ms)	4.50	5.50	4.54	5.14	4.52	5.14
9V	Load: 27W(999ms) – 40.5W(1ms)	8.10	9.90	8.52	9.12	8.54	9.14
15V	Load: 45W(999ms) – 68W(1ms)	13.5	16.5	14.4	15.0	14.4	15.0
20V	Load: 65W(999ms) – 95W(1ms)	18.0	22.0	18.8	20.1	19.3	20.1
20V	Load: 65W(999ms) – 95W(2ms)	18.0	22.0	18.5	20.1	19.2	20.1



Peak Load  
esponse Waveforr

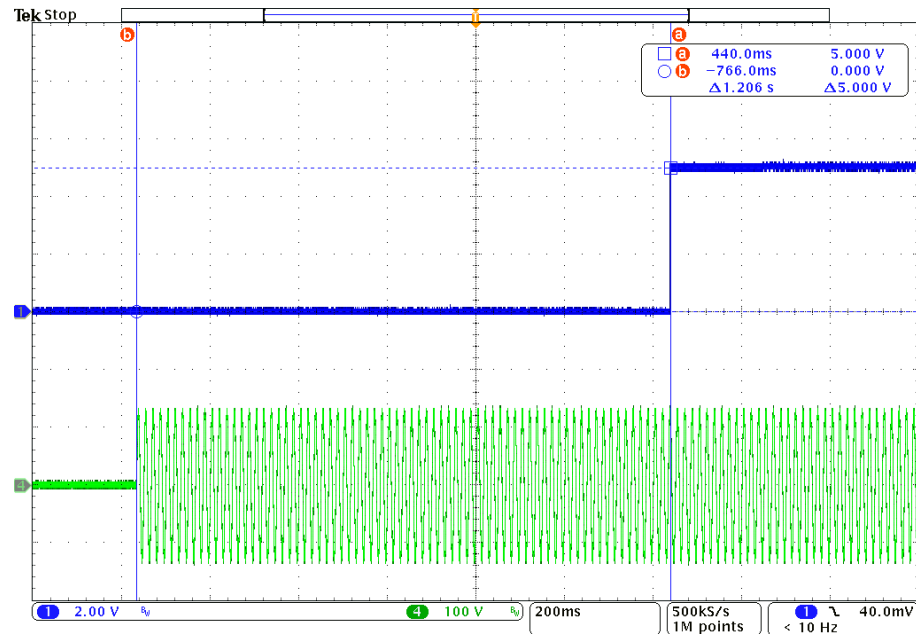
\*Note

- 1. The output voltage is measured at Cable-end. The cable impedance is 150mohm.
- 2. Refers to detail waveform as enclosed file.

# 12. TURN-ON DELAY TIME

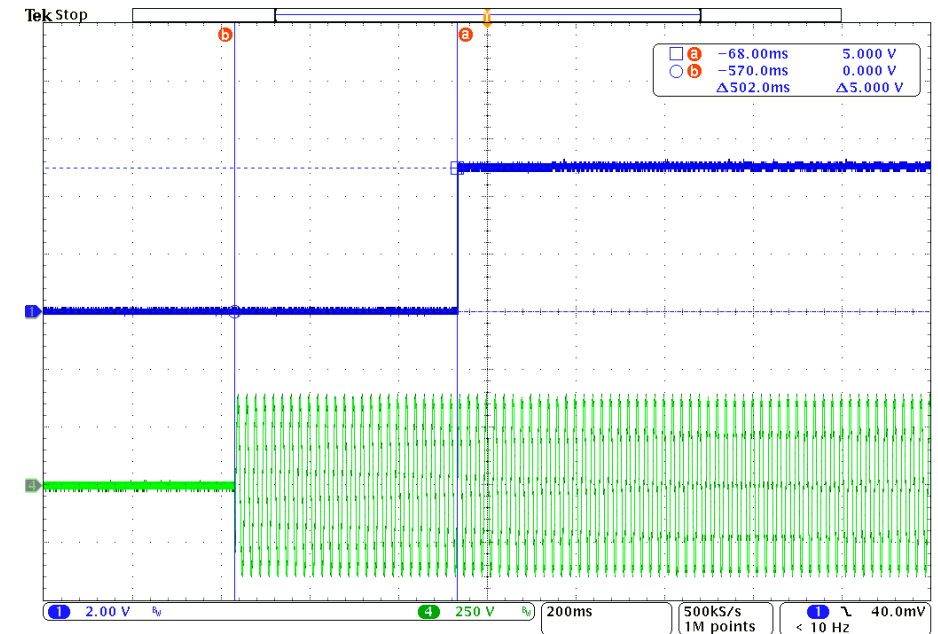
90VAC, No Load

$T_{ST\_DELAY}=1.206S$



264VAC, No Load

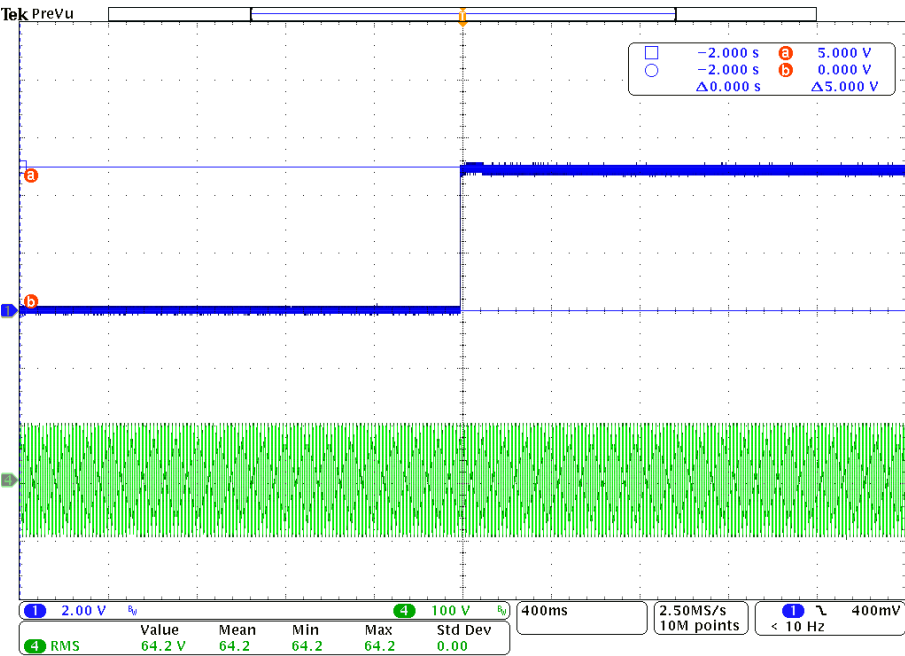
$T_{ST\_DELAY}=0.502S$



# 13. AC BROWN IN/OUT VOLTAGE

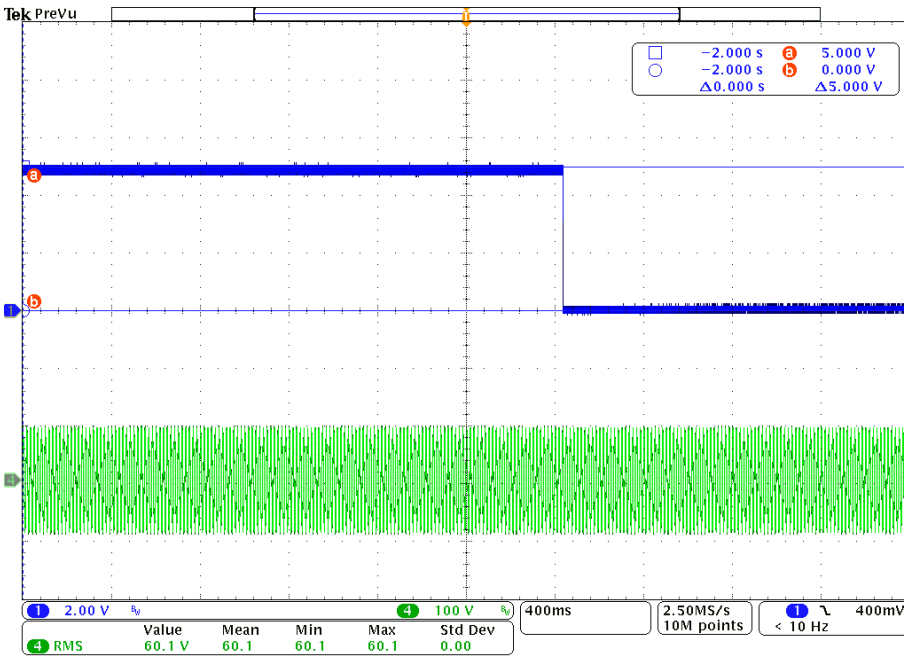
Full Load

$V_{IN\_STARTUP} = 64.2V_{AC}$



Full Load

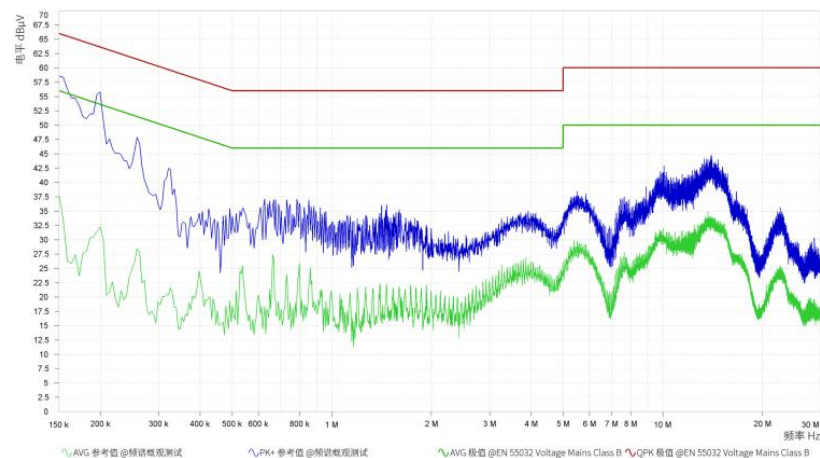
$V_{IN\_BROWNOUT} = 60.1V_{AC}$



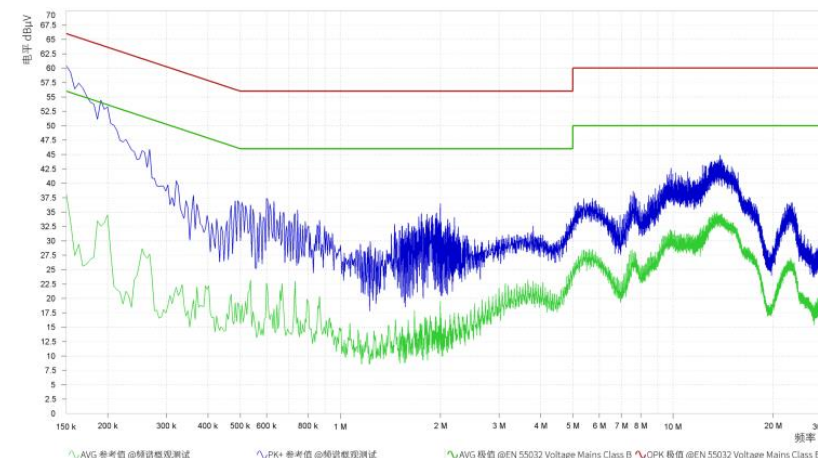


# 14. CONDUCTED EMI (@20V/3.25A)

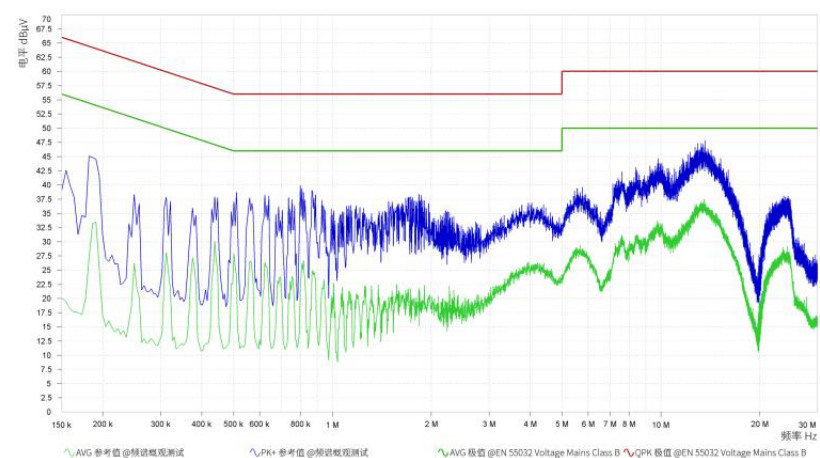
$V_{IN}=120V_{AC}/60Hz$ , Live



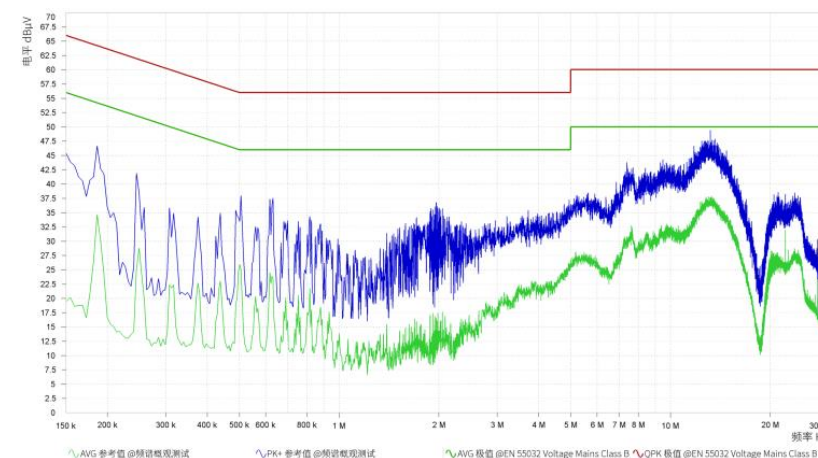
$V_{IN}=120V_{AC}/60Hz$ , Neutral



$V_{IN}=230V_{AC}/50Hz$ , Live



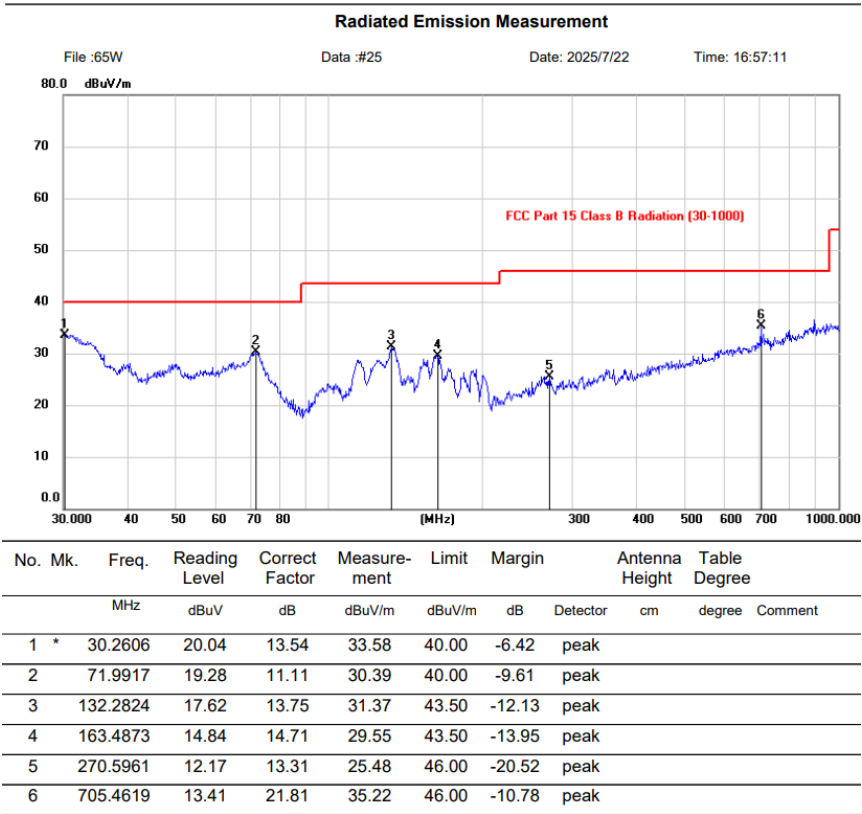
$V_{IN}=230V_{AC}/50Hz$ , Neutral



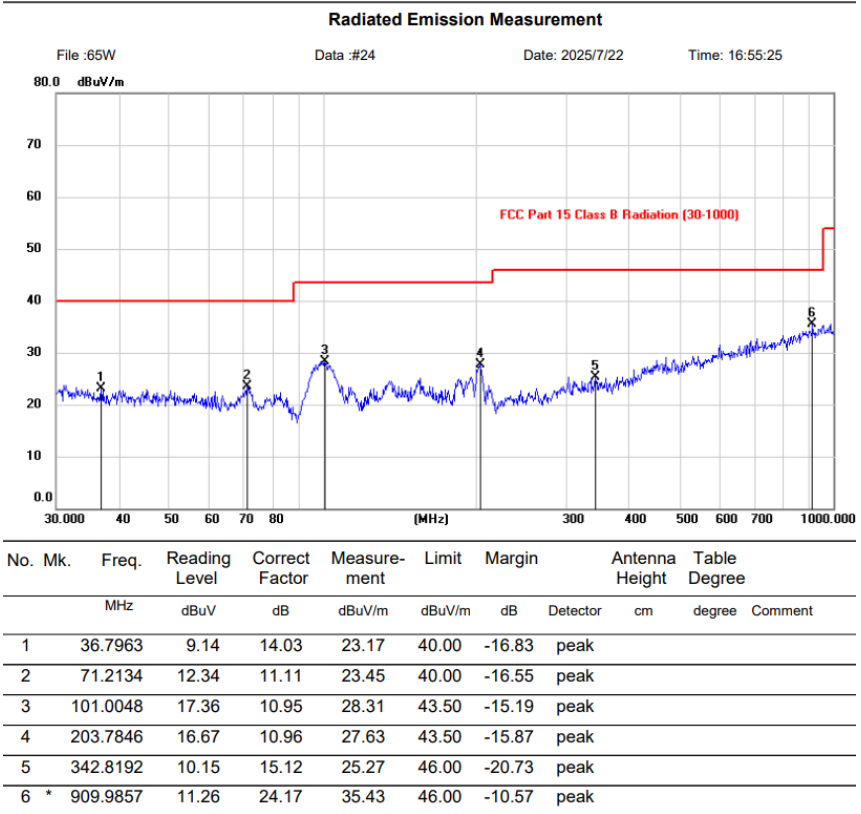
\*Note: Output “-” is connected to Earth.

# 15.1 RADIATED EMI (@20V/3.25A)

V<sub>IN</sub>=120V<sub>AC</sub>/60Hz, Vertical



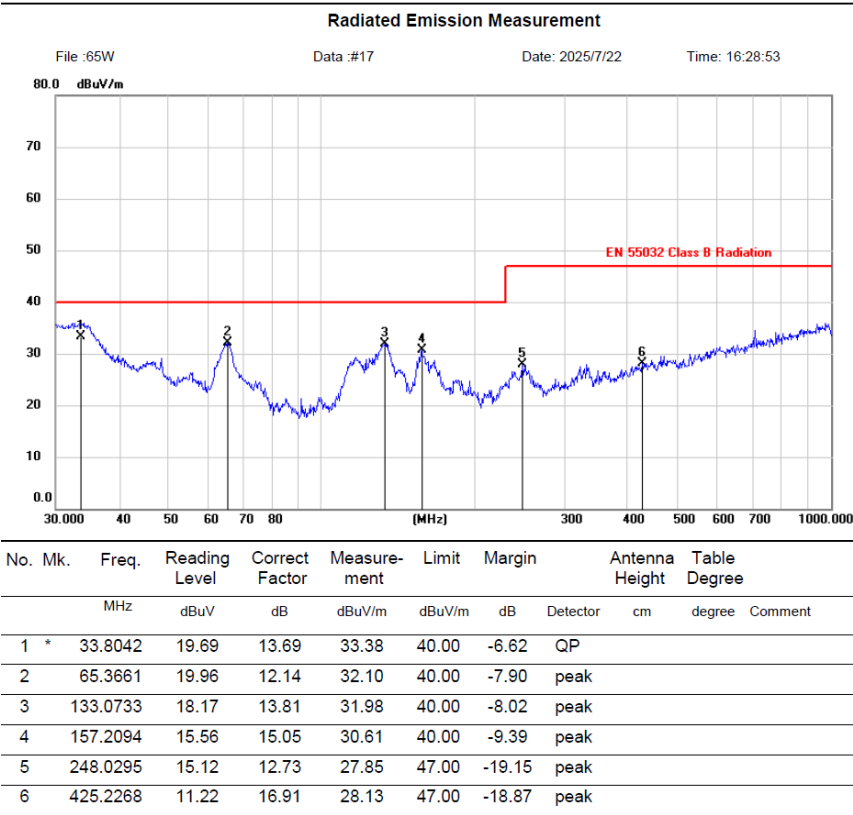
V<sub>IN</sub>=120V<sub>AC</sub>/60Hz, Horizontal



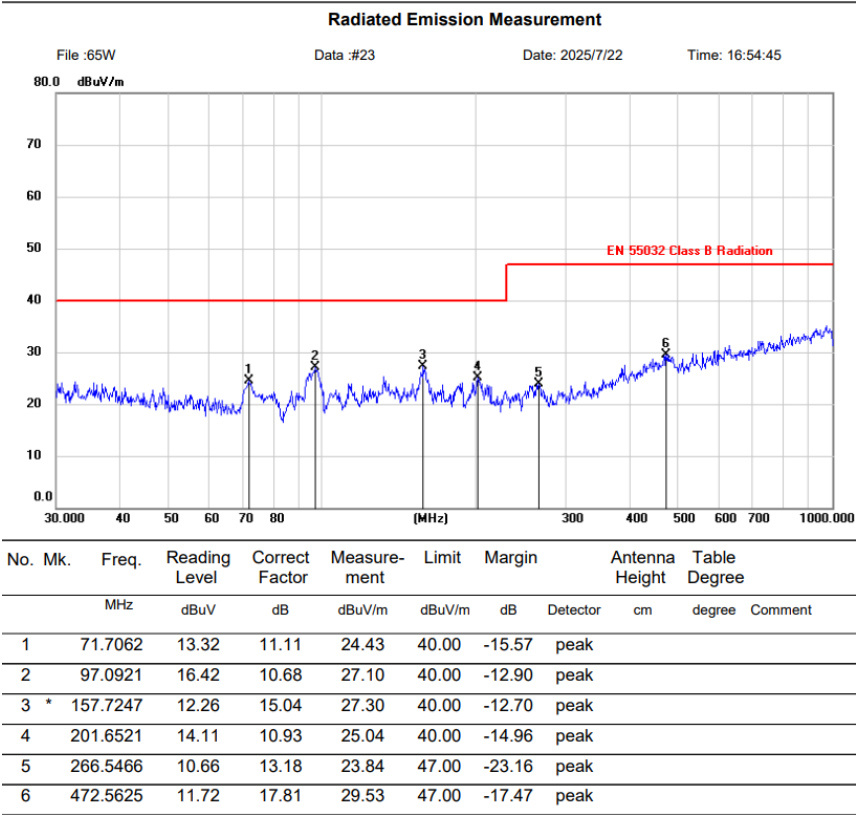
\*Note: Output “-” is connected to Earth.

# 15.2 RADIATED EMI (@20V/3.25A)

V<sub>IN</sub>=230V<sub>AC</sub>/50Hz, Vertical



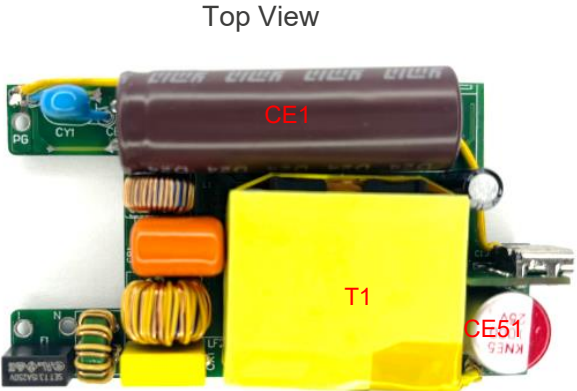
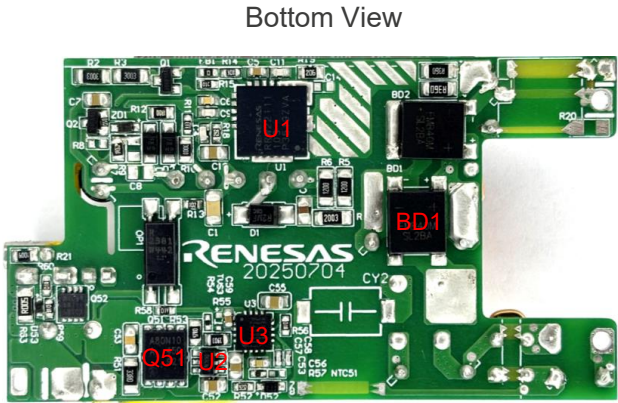
V<sub>IN</sub>=230V<sub>AC</sub>/50Hz, Horizontal



\*Note: Output “-” is connected to Earth.

# 16. THERMAL FOR CRITICAL COMPONENT

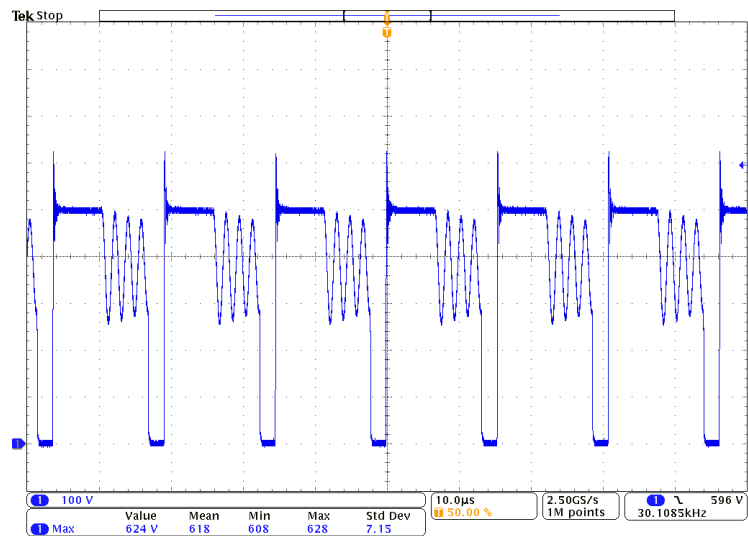
Item	V <sub>IN</sub> =90V <sub>AC</sub> , V <sub>OUT</sub> =20V I <sub>OUT</sub> =3A		V <sub>IN</sub> =264 <sub>AC</sub> , V <sub>OUT</sub> =20V I <sub>OUT</sub> =3A	
	Temp.(°C)	Rising Temp.(°C)	Temp.(°C)	Rising Temp.(°C)
BD1, FMB40M	98.8	73.8	77.0	52.0
CE1, 120uF420V	88.2	63.2	81.2	56.2
T1, ATQ27 Core	82.2	57.2	79.4	54.4
T1, ATQ27 Wire	88.3	63.3	85.6	60.6
CE51, 1000uF25V	81.7	56.7	80.5	55.5
U1, RRW22111-153 (150mΩ)	89.0	64.0	85.5	60.5
U2, iW610-08	88.7	63.7	87.2	62.2
U3, RRW30110-190	87.3	62.3	85.0	60.0
Q51, RBE067N10R1SZN6	93.1	68.1	91.7	66.7
Ambient (Chamber) Temp.(°C)	25			



\*Note:

1. Place UUT without plastic housing in a temperature chamber.

# 17. MAXIMUM DRAIN VOLTAGE OF GaN DEVICE



Test Condition (Full Load):

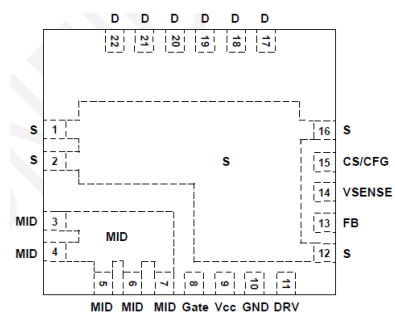
$V_{IN}=264V_{AC}$

Output=20V/3.25A

Result:

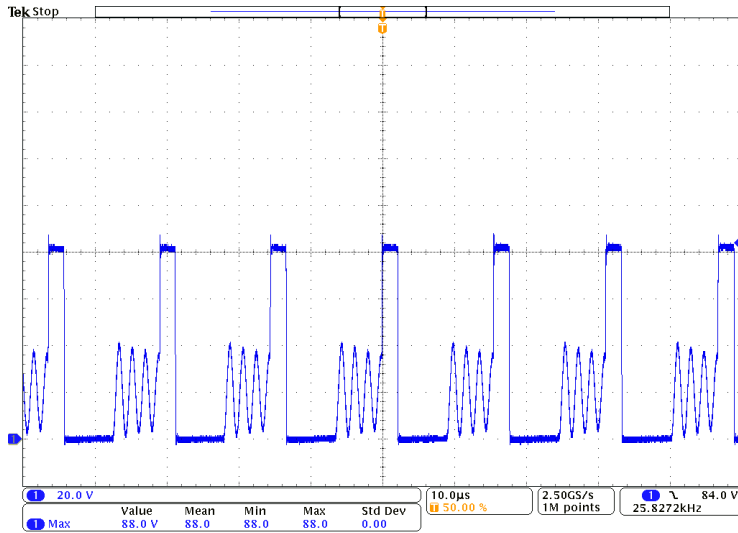
$V_{DS\_MAX}= \text{624V}$

The below is Key Performance Parameters of Integrated GaNFET Device (RRW22111-153)



$V_{DSS}$	Drain to source voltage ( $T_J = -55^{\circ}C$ to $150^{\circ}C$ )			700	V	
$V_{DSS(TR)}$ , non-repetitive	Transient drain to source voltage, non-repetitive <sup>(1)</sup>			800	V	
$V_{DSS(TR)}$ , repetitive	Transient drain to source voltage, repetitive <sup>(2)</sup>			750	V	
$V_{GSS}$	Gate to source voltage			±12	V	

## 18. MAXIMUM DRAIN VOLTAGE OF SR MOSFET



Test Condition (Full Load):

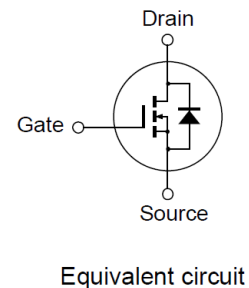
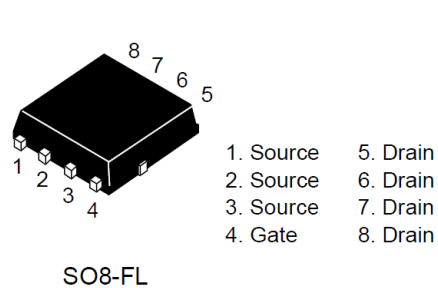
$$V_{IN}=264V_{AC}$$

Output=20V/3.25A

Result:

$$V_{DS\_MAX} = \underline{88.0V}$$

The below is Key Performance Parameters of SR MOSFET (RBE067N10R1SZN6)

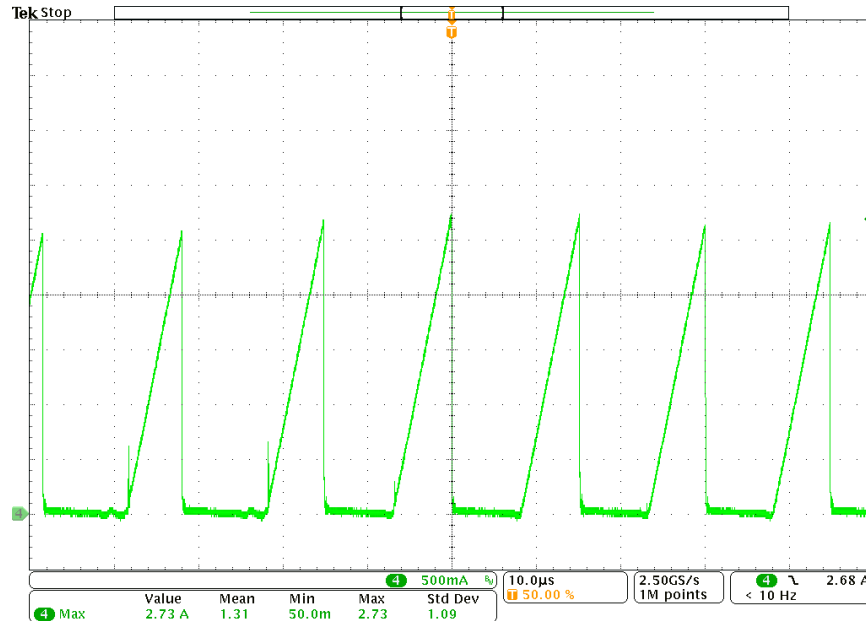


## Electrical Characteristics

(T <sub>a</sub> =25°C)						
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	10	μA	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V
Gate Leakage Current	I <sub>GSS</sub>	—	—	±1	μA	V <sub>GS</sub> = ± 20 V, V <sub>DS</sub> = 0 V
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	2.0	—	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA
Drain to Source On-state Resistance	R <sub>DS(on)</sub>	—	5.8	6.7	mΩ	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 40 <sup>Notes</sup> A
Input Capacitance	C <sub>iss</sub>	—	2800	—	pF	V <sub>DS</sub> = 50 V
Output Capacitance	C <sub>oss</sub>	—	690	—	pF	V <sub>GS</sub> = 0 V
Reverse Transfer Capacitance	C <sub>rss</sub>	—	26	—	pF	f = 100 kHz

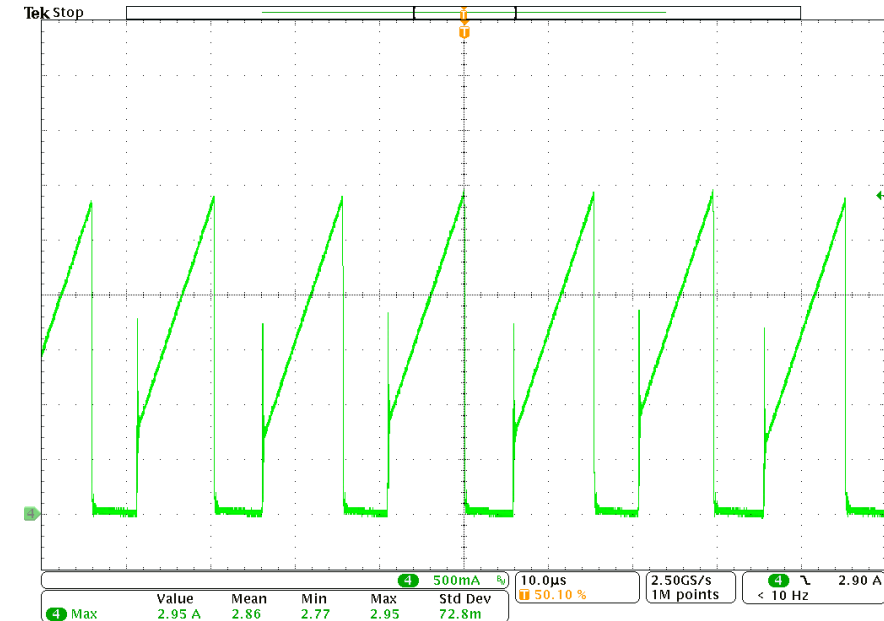
# 19. TRANSFORMER FLUX DENSITY

(N=24Ts, L=320uH, Ae=126.52mm<sup>2</sup> )



$I_p$  is monitored at 90VAC and 3.25A@20V (full load)

$$B_{MAX} = \frac{L_M \times I_{pk}}{N \times A_e} = \frac{0.32 \times 2730}{24 \times 126.52} = 0.288(\text{Tesla})$$



$I_p$  is monitored at 90VAC and 3.9A@20V (OCP)

$$B_{MAX} = \frac{L_M \times I_{pk}}{N \times A_e} = \frac{0.32 \times 2950}{24 \times 126.52} = 0.311(\text{Tesla})$$



# APPENDIX-1 BILL OF MATERIAL

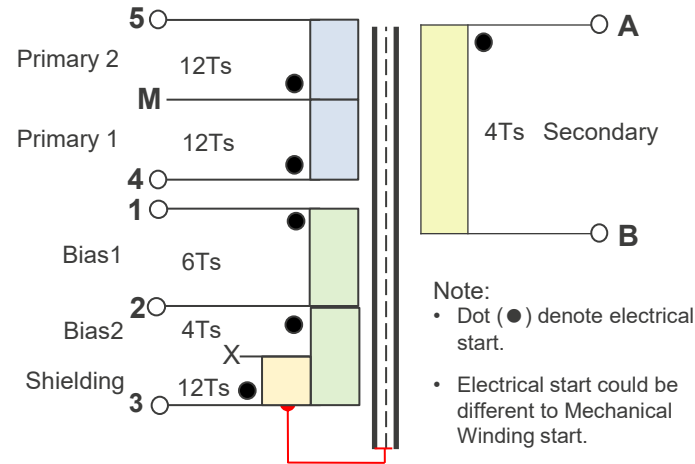
Item	Qty.	Ref. designator	Description	Manufacturer	Part no.
1	1	U1	Zero Standby Power Flyback Integrated GaN controller, QFN8*8	Renesas	RRW22111-153
2	1	U2	Synchronous Rectifier controller, SOT23-6	Renesas	iW610-08
3	1	U3	Programmable USB PD Source Controller, QFN4*4	Renesas	RRW30110-190
4	1	OP1	Photocoupler	Renesas	PS2381-1Y-AX/W
5	1	F1	Fuse, size: 8mmX4mmX7mm	Littelfuse	40013150000
6	1	LF1	Common-mode inductor, TC8×4×3, 42uH	DELI ELECTRONICS	240305191
7	1	LF2	Common-mode inductor, TC9×6×5, 18mH	B&M Magnetism	QYT09060503827018ML
8	1	L1	Differential-mode inductor, TC8×4×3-50uH/min, Wire:0.4x35.5T	B&M Magnetism	TWL031125-50uH
9	1	FB1	Multilayer Chip Ferrite Bead	Baorenhong	BEAD1206S301A30T
10	2	BD1, BD2	Fast Recovery Bridge Rectifier	Samwin	FMB40M
11	1	Q1	N-Channel Depletion-Mode Power Mosfet	PolySemi	DN906
12	1	Q2	N-Channel Depletion-Mode Power Mosfet	PolySemi	DN169
13	1	Q51	N-Channel Power Mosfet	Renesas	RBE067N10R1SZN6
14	1	Q52	Silicon N-Channel Power Mosfet	Renesas	RJK03M5DNS
15	1	T1	Transformer, Vertical type	Renesas	ATQ2714
16	1	CE1	Electrolytic capacitor, 100uF420V, Φ12.5mmX40mm	YMM	100uF420V, Φ12.5mmX40mm
17	1	CE3	Electrolytic capacitor, 10uF100V, Φ5mmX11mm	YMM	10uF100V, Φ5mmX11mm
18	1	CE51	Solid Capacitor, 1000uF25V, Φ10mmX13mm	KNSCHA	KNE5 1000UF25V 149EC0026
19	1	CB1	CBB capacitor, 1uF450V, size:12mm*17.5mm*6.5mm	NISSEI	105J450
20	1	CX1	X2 capacitor, 0.033uF275V	CARLI	0.033K275V-X2
21	1	C1	Ceramic capacitor	SAMSUNG	2.2nF, 630V, X7R, SMD-1206
22	1	C2	Ceramic capacitor	SAMSUNG	1nF, 250V, X7R, SMD-0805
23	1	C3	Ceramic capacitor	SAMSUNG	68pF, 1000V, NPO, SMD-1206
24	2	C4,C11	Ceramic capacitor	SAMSUNG	68pF, 50V, NPO, SMD-0603
25	2	C5,C7	Ceramic capacitor	SAMSUNG	2.2uF, 25V, X7R, SMD-0603
26	1	C6	Ceramic capacitor	SAMSUNG	470pF, 50V, NPO, SMD-0603
27	1	C9	Ceramic capacitor	SAMSUNG	10pF, 50V, NPO, SMD-0603
28	1	C10	Ceramic capacitor	SAMSUNG	2.2uF, 25V, X7R, SMD-0805
29	1	C13	Ceramic capacitor	SAMSUNG	100nF, 50V, X7R, SMD-0805
30	1	C51	Ceramic capacitor	SAMSUNG	220pF, 250V, X7R, SMD-0805
31	3	C52,C53,C59	Ceramic capacitor	SAMSUNG	2.2uF, 25V, X7R, SMD-0603
32	1	C55	Ceramic capacitor	SAMSUNG	2.2uF, 50V, X7R, SMD-0805
33	1	C56	Ceramic capacitor	SAMSUNG	220pF, 50V, NPO, SMD-0603
34	2	C57,C58	Ceramic capacitor	SAMSUNG	470pF, 25V, X7R, SMD-0402
35	1	CY1	Y-Cap, DIP	SHM	Y1, 330pF



# APPENDIX-2 BILL OF MATERIAL

Item	Qty.	Ref. designator	Description	Manufacturer	Part no.
36	1	D1	Diode, SMAF	PINGWEI	R2MF
37	2	D2,D4	Diode, SOD-123	Diodes	FR107
38	1	D52	Diode, SOD-323	Onsemi	BAV21
39	1	D53	Diode, SOD-523	Onsemi	1N4148WT
40	2	TVS1,TVS2	TVS, 24V, SOD-523	Nexperia	PESD24VS1UB,115
41	1	TVS3	TVS, 24V, SOD-523	Nexperia	PESD24VS1UB,115
42	1	ZD1	Zener Diode, 7.5V, SMD-323	Nexperia	PDZ7.5B,115
43	1	R1	Resistor	YAGEO	1.2K $\Omega$ $\pm$ 5%, SMD-0805
44	2	R2,R3	Resistor	YAGEO	300K $\Omega$ $\pm$ 5%, SMD-1206
45	1	R4	Resistor	YAGEO	200K $\Omega$ $\pm$ 5%, SMD-1206
46	2	R5,R6	Resistor	YAGEO	120 $\Omega$ $\pm$ 5%, SMD-1206
47	2	R7,R12	Resistor	YAGEO	1 $\Omega$ $\pm$ 5%, SMD-0805
48	1	R8	Resistor	YAGEO	750K $\Omega$ $\pm$ 5%, SMD-0603
49	1	R10	Resistor	YAGEO	330K $\Omega$ $\pm$ 1%, SMD-0805
50	1	R11	Resistor	YAGEO	33K $\Omega$ $\pm$ 1%, SMD-0603
51	2	R13, R65	Resistor	YAGEO	1K $\Omega$ $\pm$ 5%, SMD-0603
52	1	R14	Resistor	YAGEO	20 $\Omega$ $\pm$ 5%, SMD-0603
53	1	R15	Resistor	YAGEO	10K $\Omega$ $\pm$ 5%, SMD-0603
54	2	R16,R17	Resistor	YAGEO	0.36 $\Omega$ $\pm$ 1%, SMD-1206
55	1	R18	Resistor	YAGEO	2.4K $\Omega$ $\pm$ 5%, SMD-0603
56	1	R19	Resistor	YAGEO	20M $\Omega$ $\pm$ 5%, SMD-0805
57	1	R21	Resistor	YAGEO	1M $\Omega$ $\pm$ 5%, SMD-0805
58	1	R51	Resistor	YAGEO	33 $\Omega$ $\pm$ 5%, SMD-0805
59	1	R52	Resistor	YAGEO	47 $\Omega$ $\pm$ 5%, SMD-0603
60	1	R53	Resistor	YAGEO	47 $\Omega$ $\pm$ 5%, SMD-0805
61	1	R54	Resistor	YAGEO	1K $\Omega$ $\pm$ 5%, SMD-0402
62	1	R55	Resistor	YAGEO	390K $\Omega$ $\pm$ 5%, SMD-0805
63	3	R56,R59,R60	Resistor	YAGEO	100 $\Omega$ $\pm$ 5%, SMD-0603
64	1	R57	Resistor	YAGEO	0 $\Omega$ $\pm$ 5%, SMD-0402
65	1	R58	Resistor	YAGEO	1 $\Omega$ $\pm$ 5%, SMD-0603
66	1	R63	Resistor	SART	SMF12M1FR005T, 5m $\Omega$ , SMD-1206
67	2	R61,R62	Resistor	YAGEO	33 $\Omega$ $\pm$ 5%, SMD-0402
68	1	NTC51	Resistor	YAGEO	100K $\Omega$ $\pm$ 1%, SMD-0402
69	1	USB1	Connector	ZDT	5A, Type-C USB, 14Pin
70	1	PCB	PCB	Renesas	2layer side, 2oz, FR-4

# APPENDIX-3 TRANSFORMER (T1)



## ELECTRICAL SPECIFICATIONS:

1. Primary Inductance ( $L_p$ ) =  $320 \pm 5\% \mu H$  @10KHz
2. Electrical Strength = 3KV, 50/60Hz, 1Min (pins 1~5 to pins A~B)

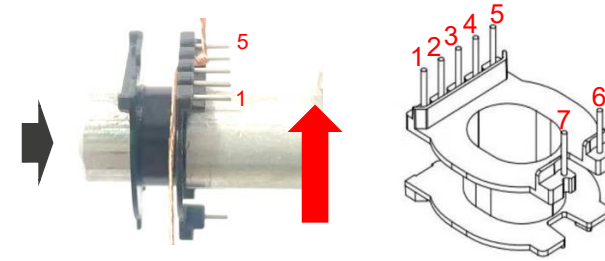
## MATERIALS:

1. Core: ATQ2714(Ferrite Material DMR97 or equivalent)
2. Bobbin: ATQ2714
3. Magnet Wires (pri): Type 2-UEW
4. Magnet wires(sec): Triple Insulated Wire
5. Layer Insulation Tape: 3M1298 or equivalent.

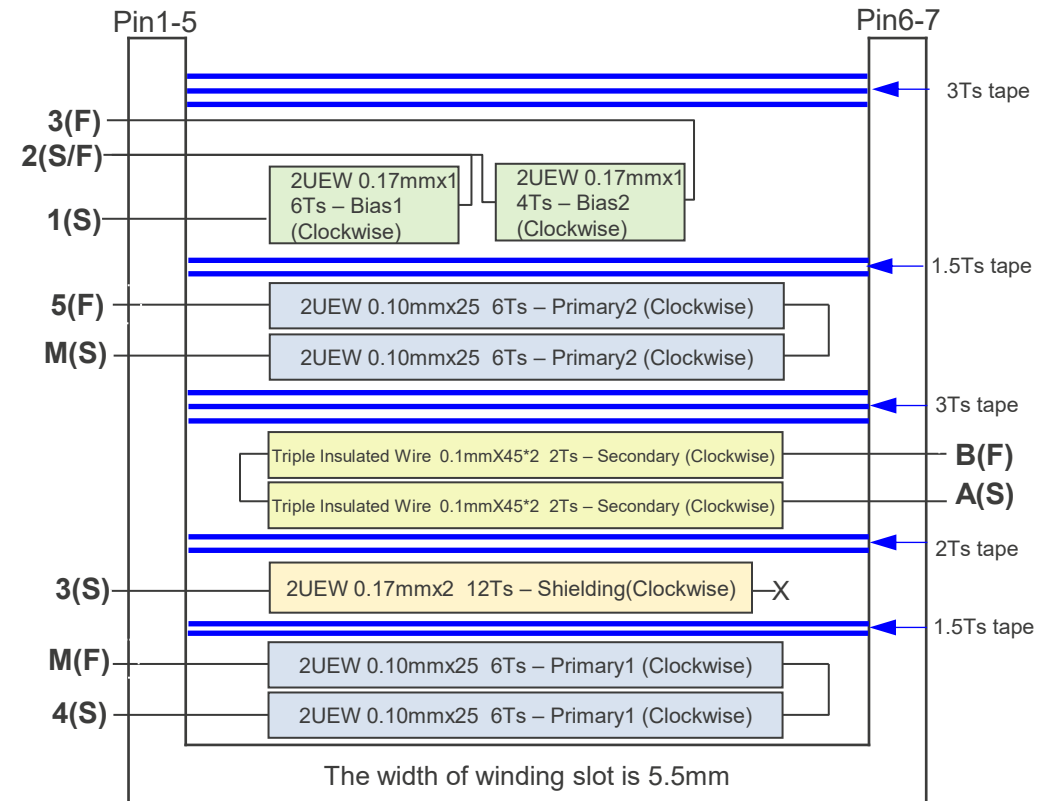
## FINISHED :

1. Vacuum varnish.
2. Core and winding around 1T copper and connect to Pin3.

Winding Start pin-4& End M to "Clockwise" direction-looking from bottom side of the Bobbin

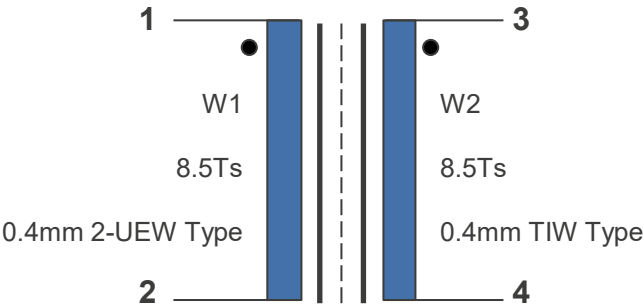


Rotating direction of winding machine



# APPENDIX-4 COMMON MODE INDUCTOR

**SCHEMATIC LF1:**

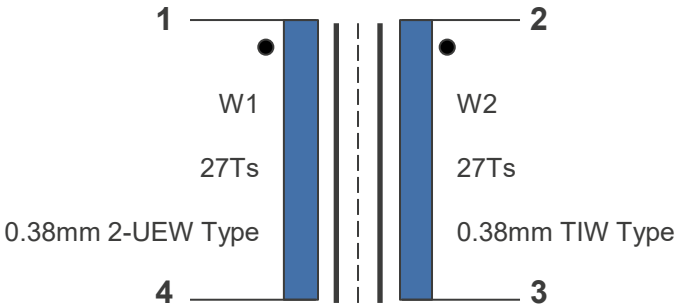


**ELECTRICAL SPECIFICATIONS:**

1. Primary Inductance (Lm) = 40uH@10KHz, 1V
2. Ferrite Material: Ni-Zn
3. CORE: T8X4X3mm
4. Electrical Strength = AC 1000V 3mA 3S

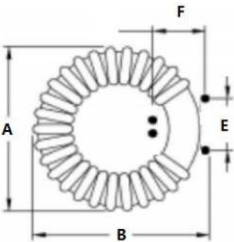


**SCHEMATIC LF2:**



**ELECTRICAL SPECIFICATIONS:**

1. Primary Inductance (Lm) = 18mH MIN@1KHz, 0.25V
2. Ferrite Material: Nanocrystalline
3. CORE: T9\*6\*5
4. Electrical Strength = AC 1000V 3mA 3S

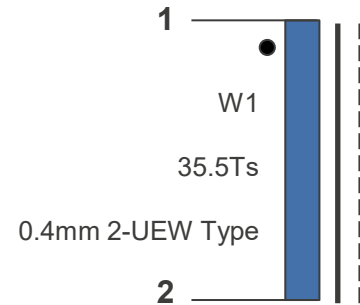


A	12.5	MAX
B	13.0	MAX
C	9.5	MAX
D	3.5	±0.5
E	7.2	±0.5
F	2.6	±0.5

# APPENDIX-5 DIFFERENTIAL MODE INDUCTOR

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## SCHEMATIC L1:



## ELECTRICAL SPECIFICATIONS:

1. Primary Inductance ( $L_m$ )  $>50\mu\text{H}@10\text{KHz}$ , 1V
2. Ferrite Material: Fe-Si
3. CORE: T8X4X3mm



# REVISION HISTORY

## Revision history

Document version	Date of release	Description of changes
V1.0	2025/07/31	Initial release
V1.1	2025/08/07	Updated PCB Layout Updated Schematic Updated Bill of materials

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